

ABSTRACT

Provided is a resin film-forming sheet excellent in reworkability and edge adhesiveness, which is stuck to a silicon wafer to form a resin film on the silicon wafer and which satisfies the following requirements (I) to (III). Requirement (I): The surface roughness (Ra) of the surface (α) of the resin film-forming sheet on the side thereof to be stuck to a silicon wafer is 50 nm or less. Requirement (II): The adhesive strength (α_1) of the surface (α) of the resin film-forming sheet to a silicon wafer is 1.0 to 7.0 N/25 mm. Requirement (III): The adhesive strength (β_1) of the surface (β) of the resin film-forming sheet on the side opposite to the side thereof to be stuck to a silicon wafer, to the pressure sensitive adhesive layer of a pressure sensitive adhesive sheet having a pressure sensitive adhesive layer formed of a specific pressure sensitive adhesive and having a thickness of 10 to 50 μm , is 4.0 N/25 mm or more.